

# PATENT ASSIGNMENT

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<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
Jing Chen	07/02/2007
Kei May Lau	07/02/2007
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<b>Name:</b>	The Hong Kong University of Science and Technology
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<b>City:</b>	Hong Kong
<b>State/Country:</b>	CHINA
<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	11564795
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**PATENT**  
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## **ASSIGNMENT**

As a below-named inventor of the U.S. patent application entitled **Low Density Drain HEMTs**, which names an inventorship of **Jing CHEN and Kei May LAU**, and which was filed **November 29, 2006** and received Serial No. **11/564,795**, I hereby sell, assign and transfer to **The Hong Kong University of Science and Technology, Clear Water Bay, Kowloon, Hong Kong**, (hereinafter referred to as ASSIGNEE), for good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, the full and exclusive right, title and interest to said invention in the United States and its territorial possessions and in all foreign countries and to all Letters Patent or similar legal protection in the United States and its territorial possessions and in all foreign countries to be obtained for said invention by said application or any division, continuation, continuation-in-part, renewal, substitute, extension, re-examination or reissue thereof or any legal equivalent thereof in the United States or any foreign country for the full term or terms of which the same may be granted, and specifically including the right to file foreign applications and claim priority therefore under the provisions of any convention or treaty;

and I also hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale;

and I further hereby covenant that I will, upon ASSIGNEE'S request, promptly provide ASSIGNEE with all pertinent facts and documents, relating to said application, to any invention disclosed therein, or to any of said Letters Patent or legal equivalents thereof in the United States or in foreign countries, as may be known and accessible to me, and that I will testify and give evidence as to the same in any litigation or interference which may arise, and that I will promptly execute and deliver to ASSIGNEE or its legal representative, without charge but at Assignee's expense, any and all papers, instruments or affidavits which may be required, necessary or desirable for the purpose of applying for, obtaining, maintaining, issuing or enforcing said application and said Letters Patent and said equivalents thereof in the United States or in any foreign country; and I further authorize ASSIGNEE or its legal representative to make any submissions or true declarations which may be needed in connection with the prosecution of this application or related applications in the U.S. or in other countries, consistent with the requirements of the applicable country;

AND I HEREBY AUTHORIZE AND REQUEST the issuing authority to issue any and all United States and foreign patents granted on said invention to ASSIGNEE, its successors and assigns.

IN WITNESS WHEREOF, this Assignment has been executed on the date set forth below.

Inventor: Jing CHEN

Date: 7/2/07 Signature: Jing Chen

Residence: Tower 6, Flat 6B, Senior Staff Quarter, Hong Kong University of Science and Technology, Clear Water Bay, Kowloon, Hong Kong

Inventor: Kei May LAU

Date: 7/2/07 Signature: Kei May Lau

Residence: Tower 15, 4A, HKUST, Clear Water Bay, Kowloon, Hong Kong